

# DATA SHEET

Order code	Manufacturer code	Description
47-3309	n/a	1N4148 75V 200 MA SIGNAL DIODE. (RC)
47-3311	n/a	1N4148 SIGNAL DIODE (5K BOX) (RC).

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The enclosed information is believed to be correct, Information may change ±without noticeqdue to product improvement. Users should ensure that the product is suitable for their use. E. & O. E.	Revision A 20/02/2007

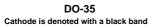
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January 2007

# 1N/FDLL 914/A/B / 916/A/B / 4148 / 4448 **Small Signal Diode**







THE PLACEMENT OF THE EXPANSION GAP HAS NO RELATIONSHIP TO THE LOCATION OF THE CATHODE TERMINAL

#### LL-34 COLOR BAND MARKING

LL 04 GOLOR BARB MARRING				
	DEVICE	1ST BAND	2ND BAND	
	FDLL914	BLACK	BROWN	
	FDLL914A	BLACK	GRAY	
	FDLL914B	BROWN	BLACK	
	FDLL916	BLACK	RED	
	FDLL916A	BLACK	WHITE	
	FDLL916B	BROWN	BROWN	
	FDLL4148	BLACK	BROWN	
	FDLL4448	BROWN	BLACK	

-1st band denotes cathode terminal and has wider width

# Absolute Maximum Ratings\* Ta=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage	100	V
I <sub>O</sub>	Average Rectified Forward Current	200	mA
I <sub>F</sub>	DC Forward Current	300	mA
i <sub>f</sub>	Recurrent Peak Forward Current	400	mA
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second Pulse Width = 1.0 microsecond	1.0 4.0	A A
T <sub>STG</sub>	Storage Temperature Range	-65 to + 175	°C
$T_J$	Operating Junction Tempera	-65 to + 175	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of the diode may be impaired.

# **Thermal Characteristics**

Symbol	Parameter	Max.	Units	
Symbol	i arameter	1N/FDLL 914/A/B / 4148 / 4448		
$P_{D}$	Power Dissipation	500	mW	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	300	°C/W	

These ratings are based on a maximum junction temperature of 200 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# Electrical Characteristics\* T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Max.	Units
V <sub>R</sub>	Breakdown Voltage	$I_R = 100 \mu A$ $I_R = 5.0 \mu A$	100 75		V V
V <sub>F</sub>	1N916 1N914/916/414 1N914A/916 1N916	1 :	620 630	720 730 1.0 1.0 1.0	mV mV V V
I <sub>R</sub>	Reverse Leakage	V <sub>R</sub> = 20V V <sub>R</sub> = 20V, T <sub>A</sub> = 150°C V <sub>R</sub> = 75V		25 50 5.0	nA μA μA
C <sub>T</sub>	Total Capacitance 1N916A/B/4448 1N914A/B/4148	V <sub>R</sub> = 0, f = 1.0MHz V <sub>R</sub> = 0, f = 1.0MHz		2.0 4.0	pF pF
t <sub>rr</sub>	Reverse Recovery Time	$I_F = 10mA, V_R = 6.0V (600mA)$ $I_{rr} = 1.0mA, R_L = 100\Omega$		4.0	ns

<sup>\*</sup> Non-recurrent square wave PW = 8.3ms

# **Typical Characteristics**

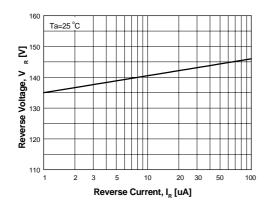


Figure 1. Reverse Voltage vs Reverse Current BV - 1.0 to  $100\mu A$ 

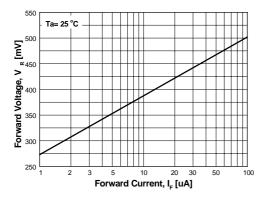
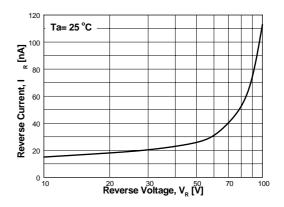


Figure 3. Forward Voltage vs Forward Current VF - 1 to  $100 \mu A$ 



GENERAL RULE: The Reverse Current of a diode will approximately double for every ten (10) Degree C increase in Temperature

Figure 2. Reverse Current vs Reverse Voltage IR - 10 to 100V

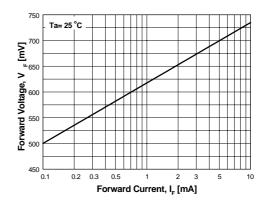


Figure 4. Forward Voltage vs Forward Current VF - 0.1 to 10mA

# Typical Characteristics (Continued)

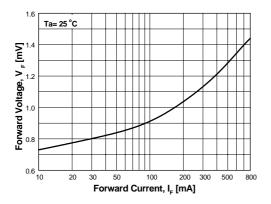


Figure 5. Forward Voltage vs Forward Current VF - 10 to 800mA

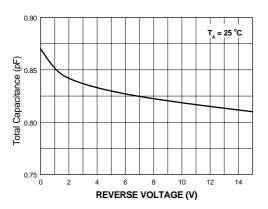


Figure 7. Total Capacitance

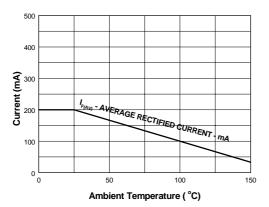


Figure 9. Average Rectified Current  $(I_{F(AV)})$  vs Ambient Temperature  $(T_A)$ 

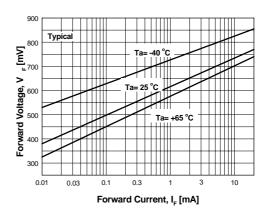
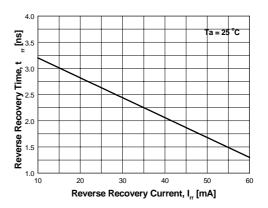


Figure 6. Forward Voltage vs Ambient Temperature VF - 0.01 - 20 mA (- 40 to +65°C)



IF = 10mA , IRR = 1.0 mA , Rloop = 100 Ohms
Figure 8. Reverse Recovery Time vs
Reverse Recovery Current

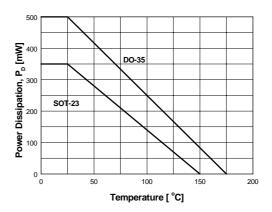


Figure 10. Power Derating Curve

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Datasheet Identification	Product Status	Definition
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